1	10. Newly Added) A method of mounting components
2	according to claim 9, wherein step c) includes the step of modifying said
3	mounting locations based on step b), wherein said components are
4	mounted in step d) based on said modified mounting locations.
1	11. (Newly Added) Apparatus for mounting components
2	on a board, comprising:
3	a memory in which is situated location values which
4	correspond to where components are intended to be mounted on said
5	board;
6	a locator for identifying solder locations which correspond to
7	respective locations of solder on said board;
8	a mounter for mounting said components based on said
9	location values and said solder locations.
1	12. (Newly Added) Apparatus for mounting components
2	according to claim 11, further comprising a calculation unit which
3	modifies said location values based on said solder values, wherein said
4	mounter mounts said components based on said modified location values.

Respectfully Submitted,

Lawrence E. Ashery, Reg. No. 34,515 Attorney for Applicants

Kethleen

LEA/ap

Dated: September 5, 2001

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The Assistant Commissioner for Patents is hereby authorized to charge payment to Deposit Account No. 18-0350 of any fees associated with this communication.

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Kathleen Libby

VERSION WITH MARKINGS TO SHOW CHANGES MADE CLAIMS:

Claims 9-12 have been newly added.